

2D Materials for Energy Harvesting Application

9 September 2024

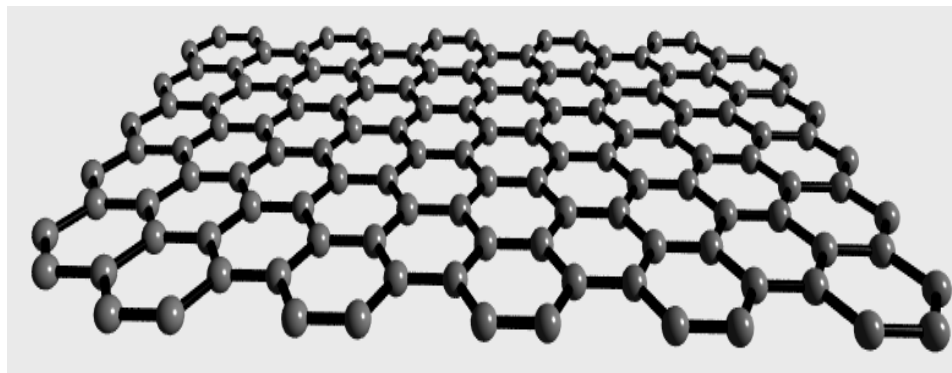
AMO Intro



AMO GmbH

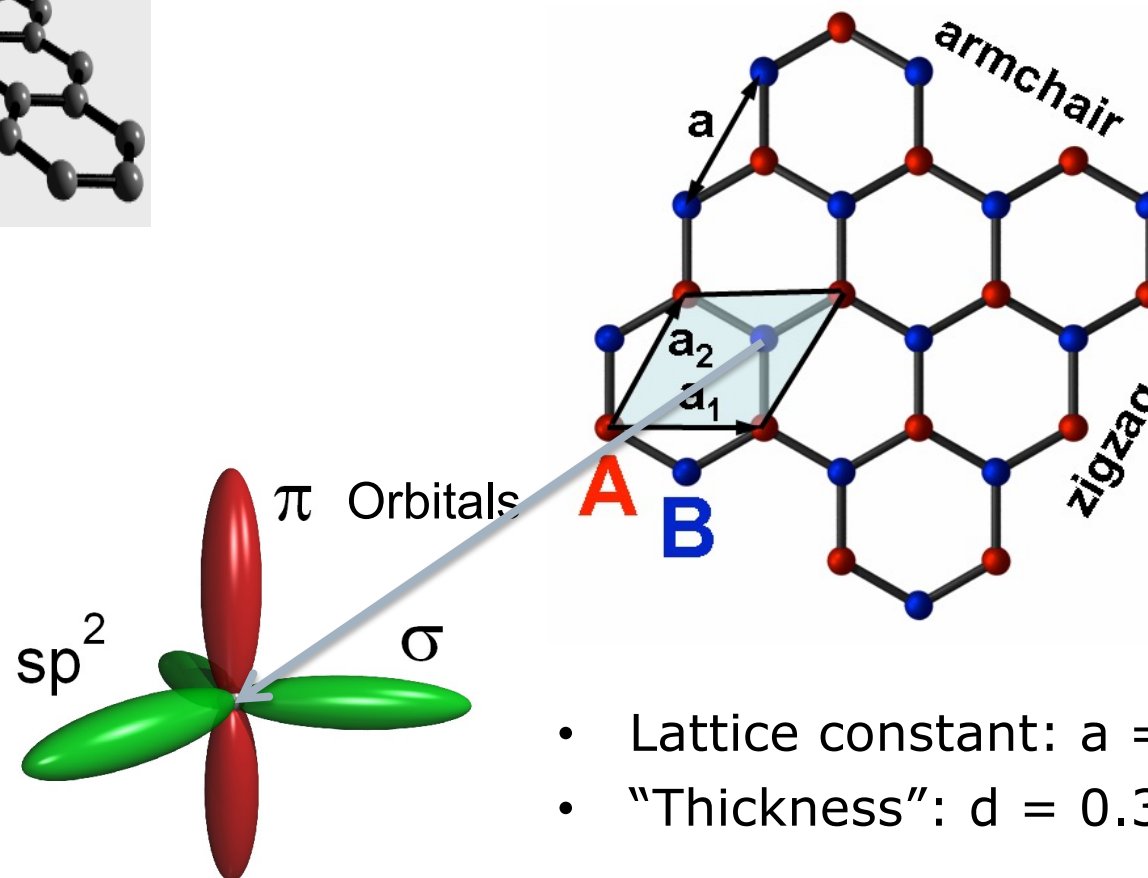
- High-Tech SME / Institute (non-profit) / Research Foundry
- 400 m² clean room
- 80 staff members in 35 funded R&D projects
- > 100 R&D partners across Europe and beyond
- Silicon technology, Nanofabrication & New Materials
- Targeted applications
 - Nanoelectronics, Sensors, Flexible Electronics
 - Nanophotonics
 - Quantum Technologies
 - Neuromorphic Computing
 - Environmental Nanotechnology
- Mission: Technology Transfer
 - R&D Partners & Start Ups (Black Semiconductor, Protemics, AMOtronic)

Graphene: Crystal Properties



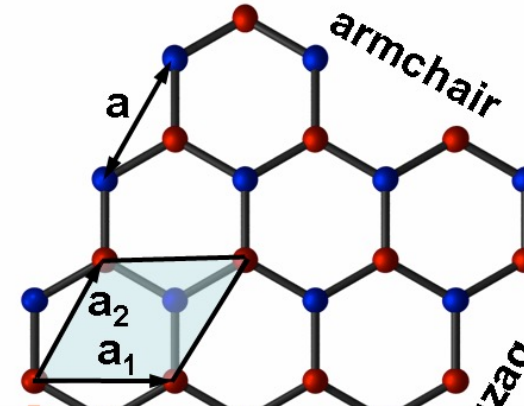
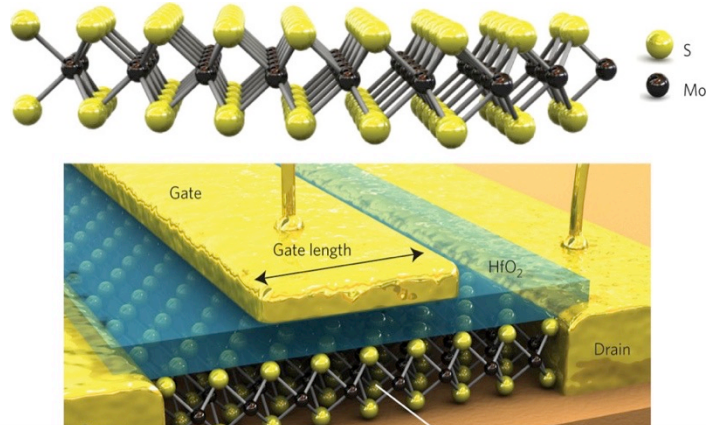
- sp^2 bonded carbon atoms ($\sim 4,3\text{eV}$)
- Graphite: stacked layers of graphene
- interlayer bond: v.d. Waals

2D-crystal lattice



- Lattice constant: $a = 0.246 \text{ nm}$
- "Thickness": $d = 0.34 \text{ nm}$

Semiconductors & Insulators



...over 1000 2D crystals!

Molybdenum Disulfide (MoS₂)

Transition Metal Dichalcogenides (TMDs)

- $E_g = 1.8 \text{ eV}$
- $\mu_{\text{MoS}_2} \approx 100 \text{ cm}^2/\text{Vs}$

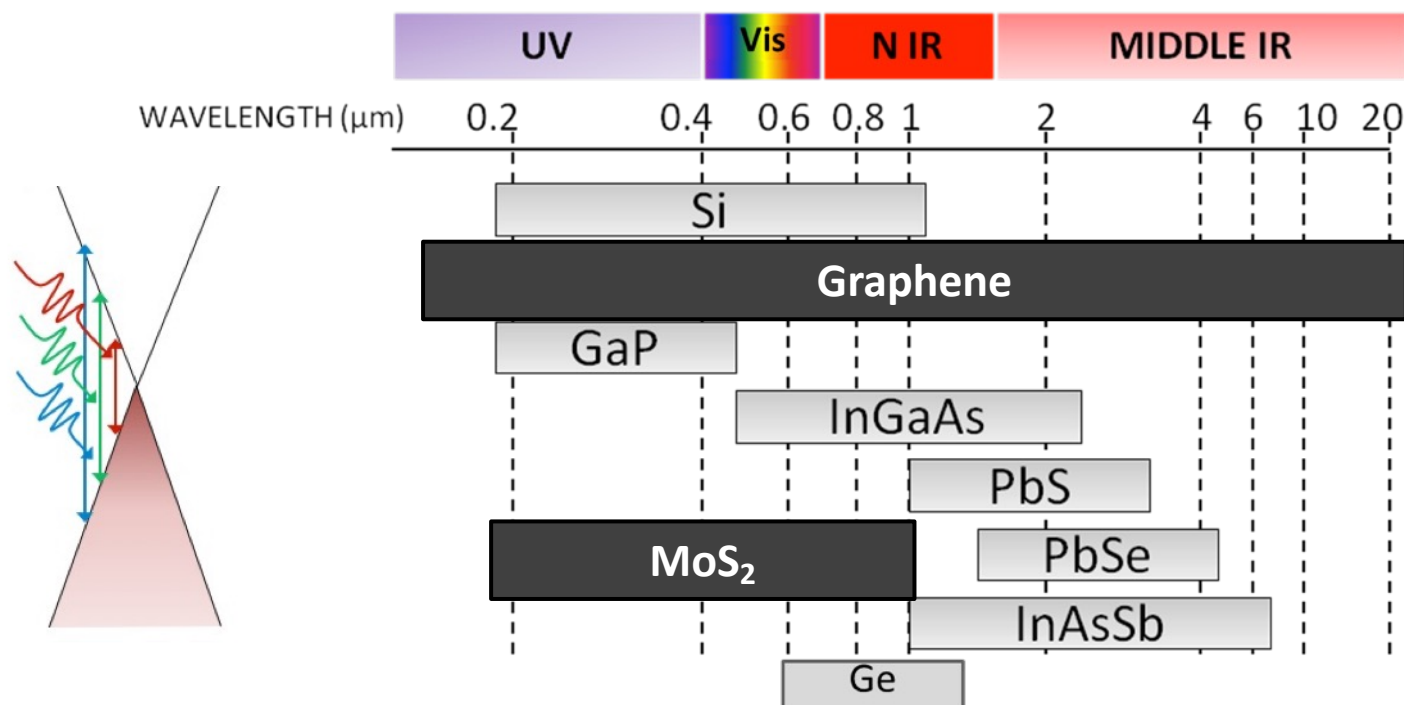
Radisavljevic, Nat. Nanotech. 2011.

Hexagonal Boron Nitride (h-BN)

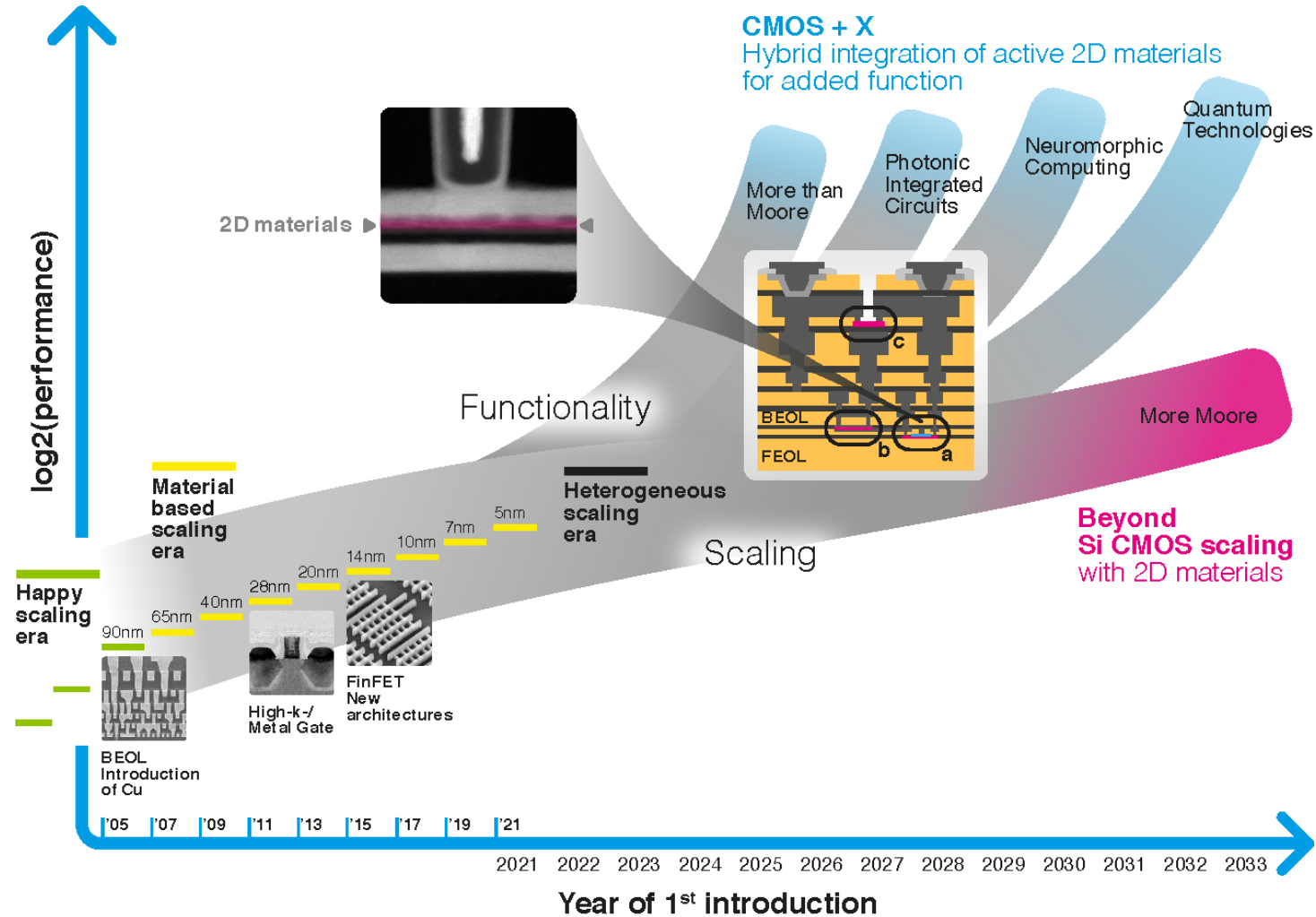
- $E_g = 5.9 \text{ eV}$
- **A** = Boron
- **B** = Nitrogen

Graphene and 2D materials:

- + Ultra broad band spectral response (graphene, PtSe₂)
- + Large scale production (CVD)
- + High conductivity
- + mechanical Flexibility
- + Integrability
- ± Gate tunability
- Low absolute absorption



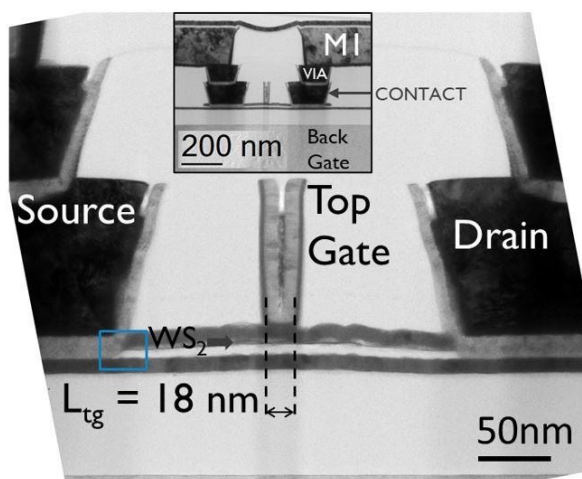
CMOS+X



Lemme *et al.*, Nat. Comm., 2022

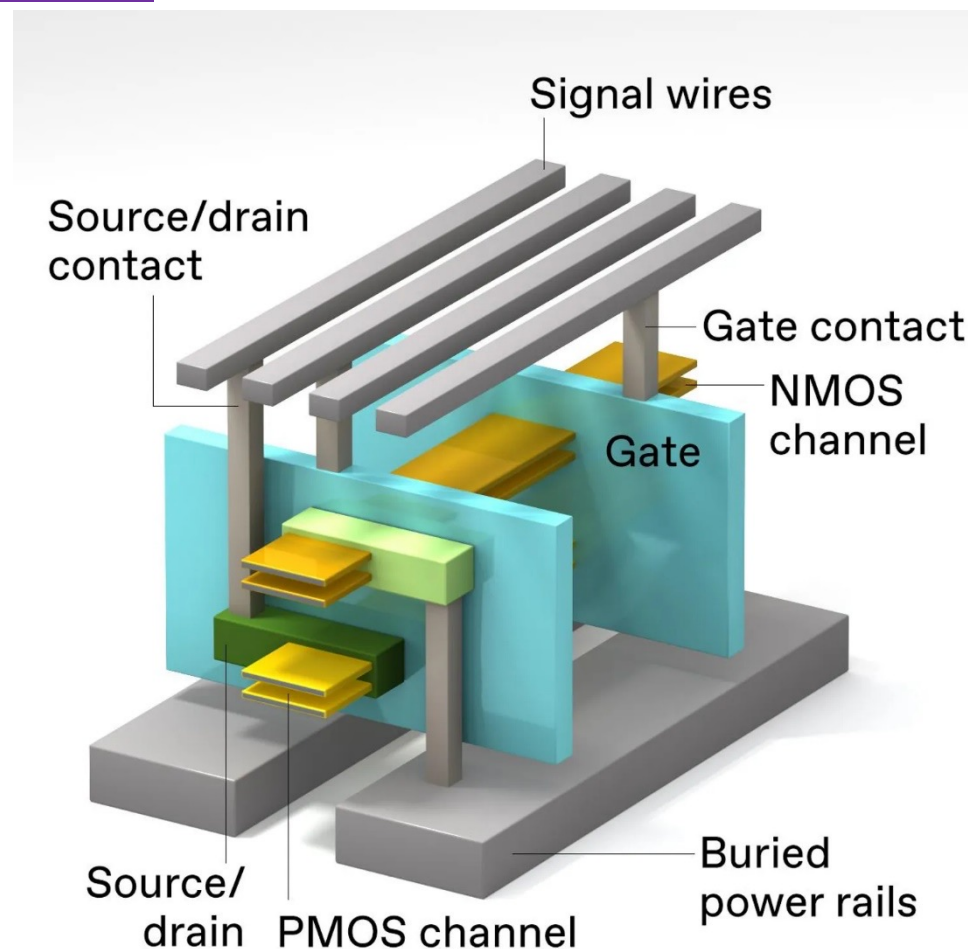
More Moore

- 2D Nanosheet FETs
 - Ultimate electrostatic control
 - No loss of mobility
 - BEOL integration → 3D



Source: IMEC

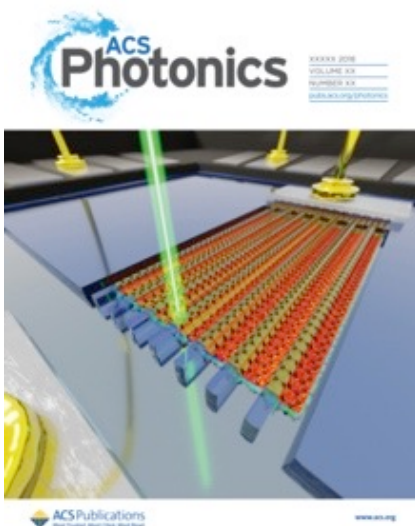
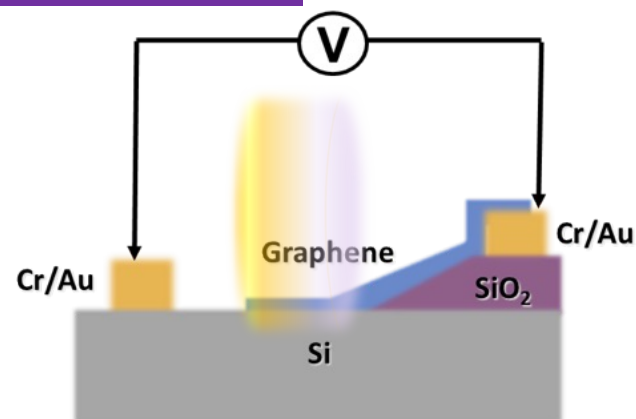
<https://www.imec-int.com/en/articles/imec-introduces-2d-materials-logic-device-scaling-roadmap>



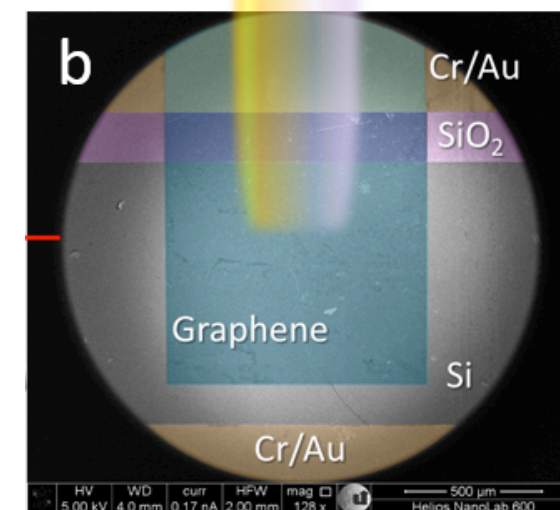
Radosavlevic et al., IEEE Spectrum, 2022

Graphene-Silicon Schottky Diodes

- Vertical Schottky diode architecture
- High responsivity
- Ease of Integration
- Potential for infrared detection
- Potential for flexible substrates



Riazimehr *et al.*, SSE, 2016
 Riazimehr *et al.*, ACS Photonics, 2017
 Riazimehr *et al.*, ACS Photonics, 2019



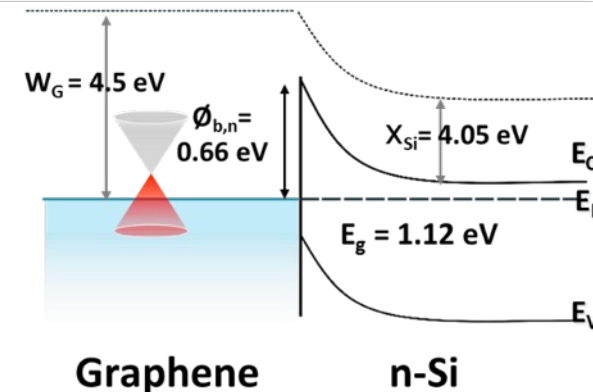
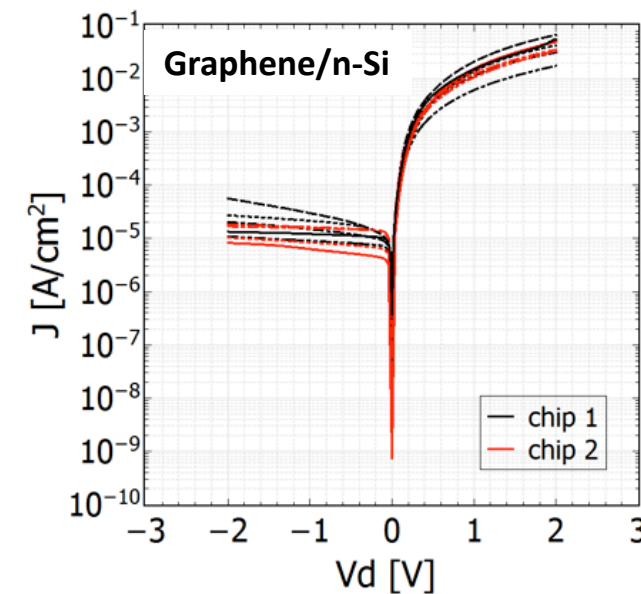
Graphene-Silicon Schottky Diodes

- Vertical device architecture
- High responsivity
- Ease of Integration
- Potential for infrared detection
- Potential for flexible substrates

- Shockley equation:

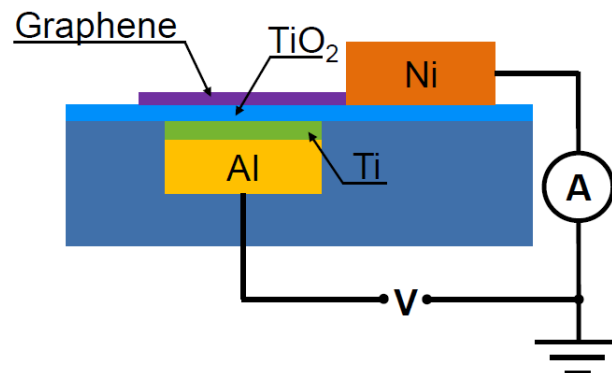
$$I = I_S \left[\exp \left(\frac{qV_d}{nk_B T} \right) - 1 \right]$$

- Ideality factor $n = 1.52$
- Barrier height $\phi_{b,n} = 0.66$ eV
- p doping due to exposure to ambient atmosphere



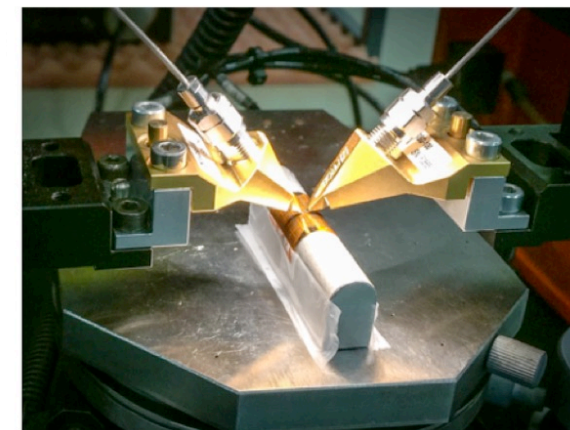
Riazimehr *et al.*, Solid State Electronics, 2016

Metal-Insulator-Graphene Diodes

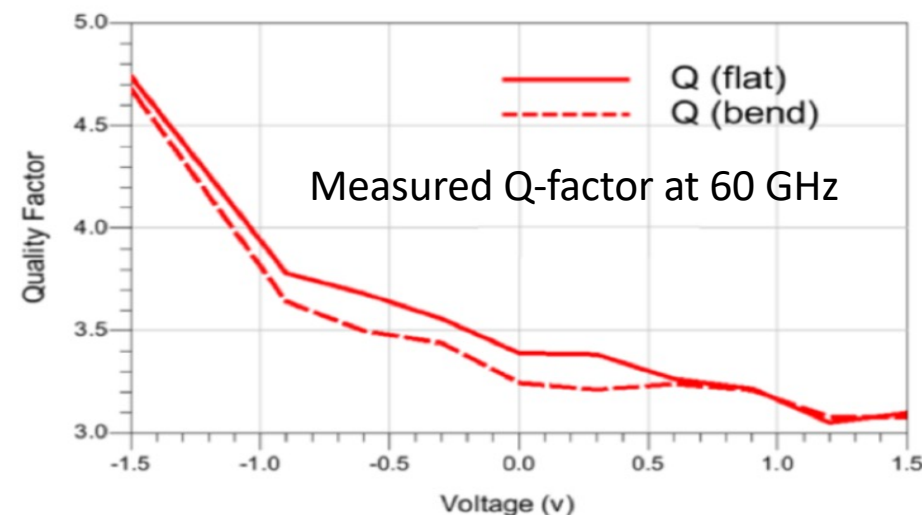
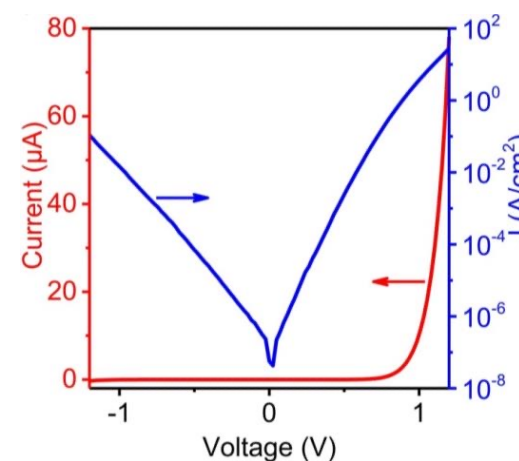
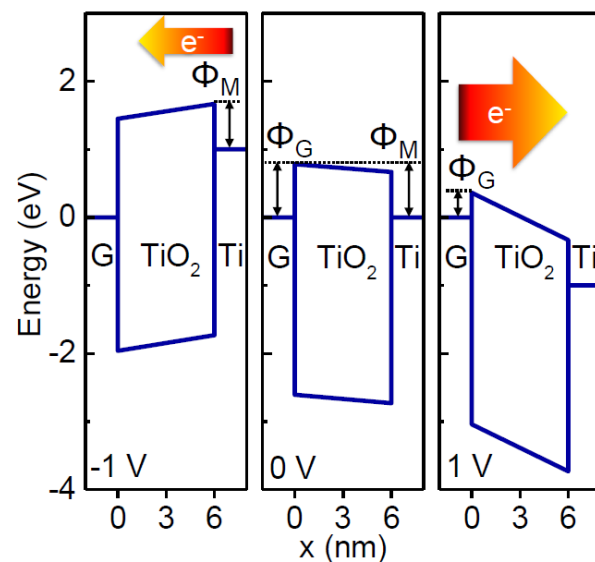


Shaygan *et al.* Nanoscale, 2017
Wang *et al.*, ACS Appl. El. Materials, 2019
Wang *et al.*, Adv. El. Mat, 2021

RF measurements of flexible diodes

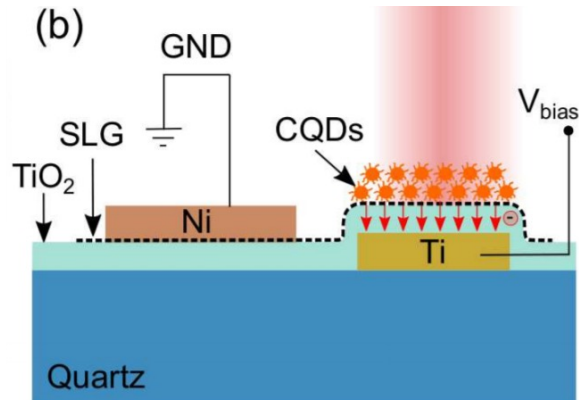


Bias induced barrier lowering

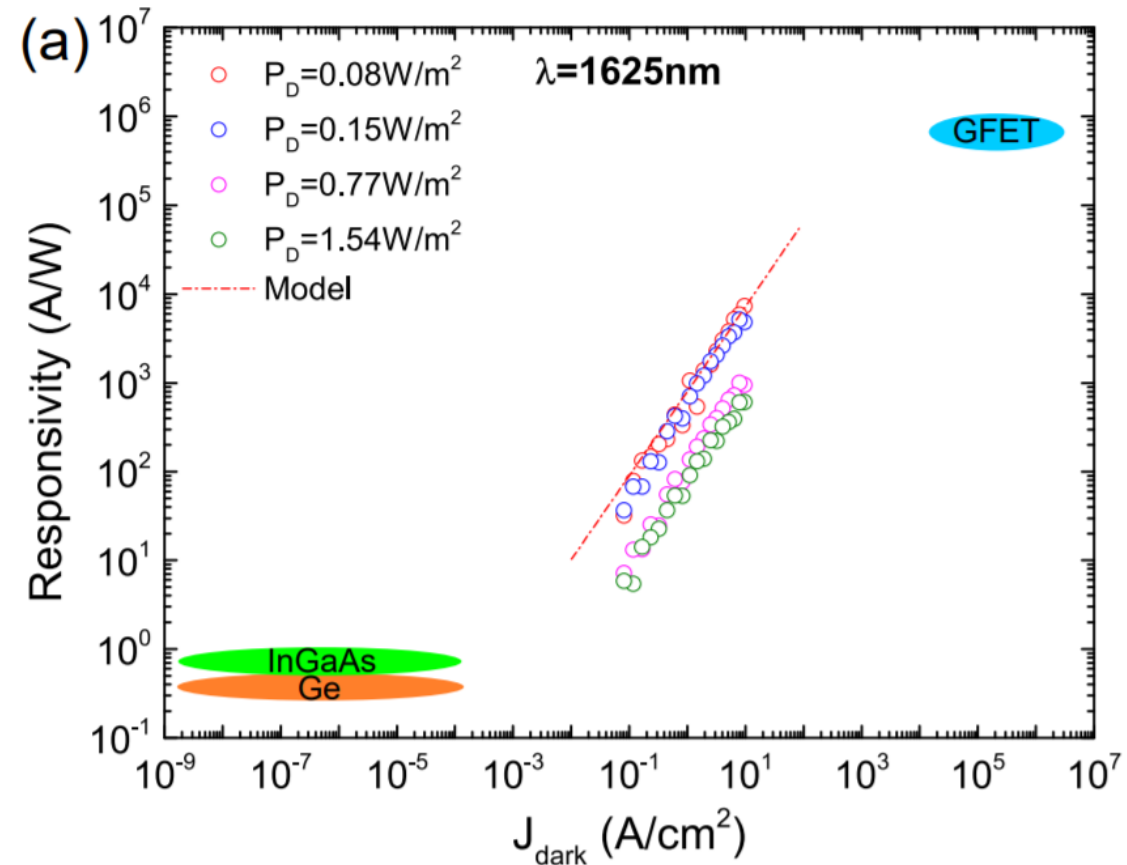
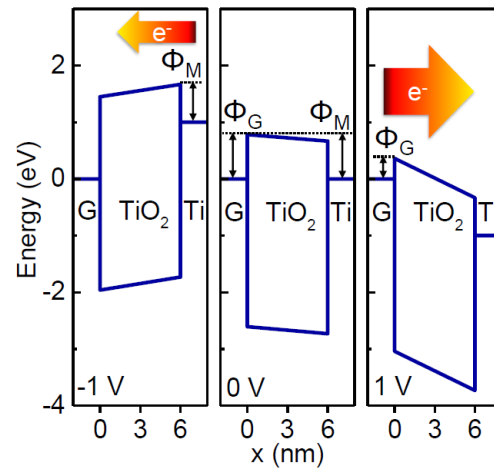


ions
ms

Graphene / Quantum Dot Integration for IR Photodetection



Bias dependent barrier



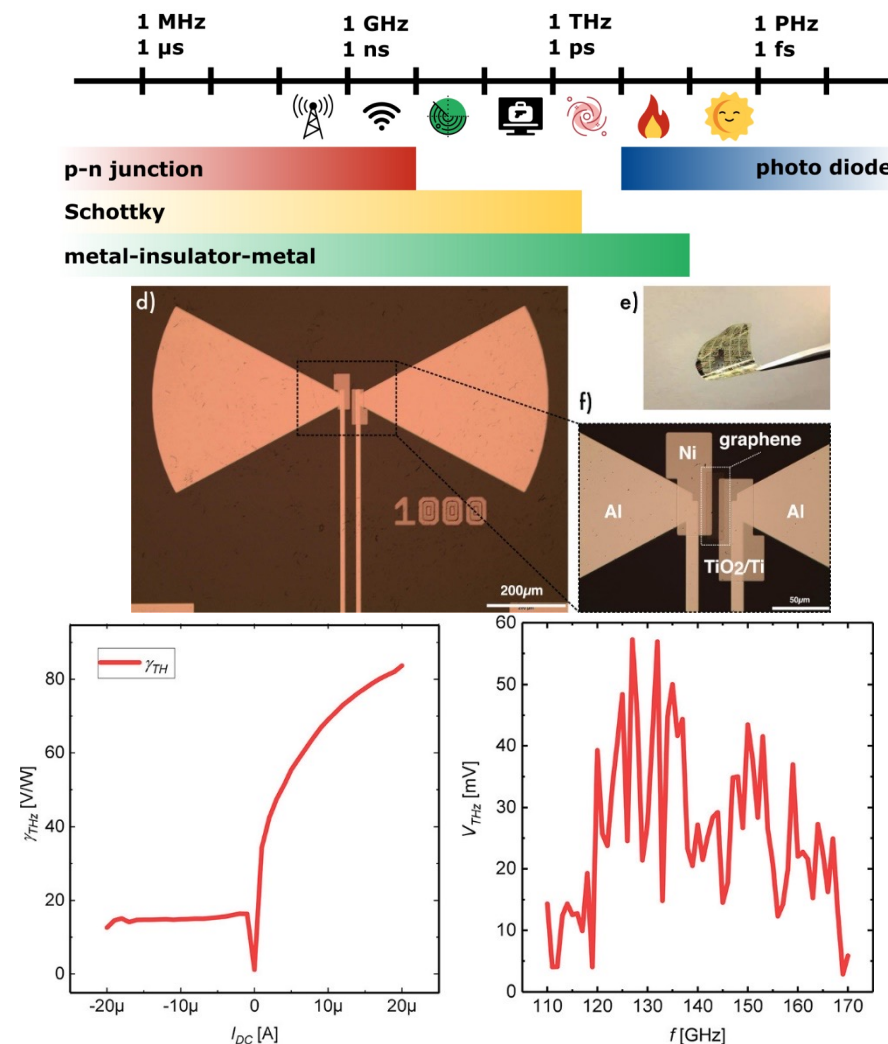
De Fazio *et al.* ACS Nano 2020

Rectennas

- High RF-to-DC conversion efficiency demonstrated with monochromatic MHz-GHz sources (>90% at 2.45 GHz)
- Bottleneck in adapting to higher frequencies: response time of the rectifier
- Metal-insulator-metal diodes
 - Fast response time due to majority charge carrier transport
 - Usually low responsivity, low rectification efficiency
- Metal-insulator-graphene diodes
 - Enhanced responsivity
 - Reduced junction capacitance increases frequency response

Sinohara, *River Publishers* **2017**

Hemmetter *et al.*, *ACS Applied Electronic Materials* **2021**



Ballistic Rectification

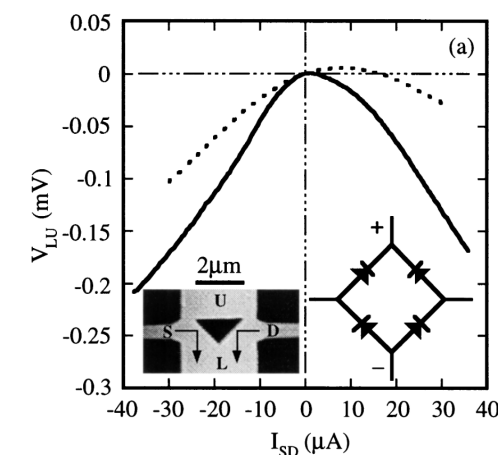
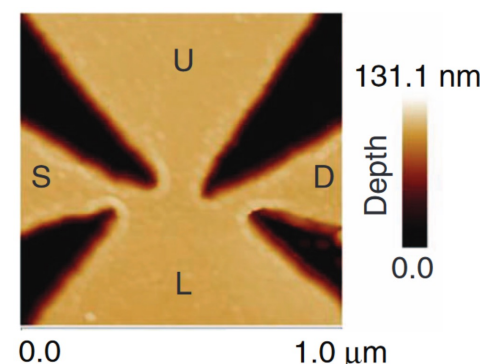
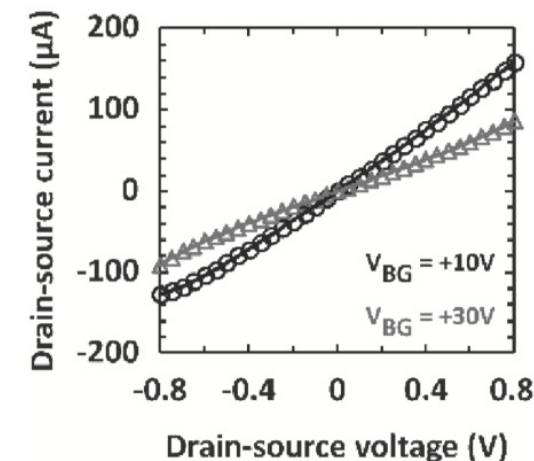
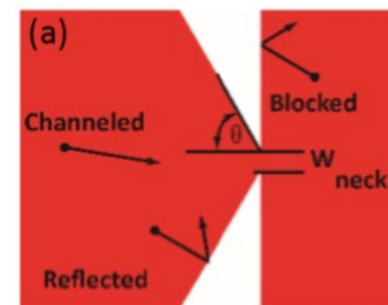
- Ballistic rectifier
 - Charge carrier scattering occurs primarily at the device edges
 - No potential barrier inhibits current → zero-bias operation
- Two-terminal and four-terminal devices have been demonstrated
 - GaAs-AlGaAs and InAs/AlGaSb heterostructures
 - Si nanowires
 - graphene
- Long mean free path requires high charge carrier mobility

Passi *et al.*, 2017 *Silicon Nanoelectronics Workshop*, 2017

Song *et al.*, *Phys. Rev. Lett.* 1998

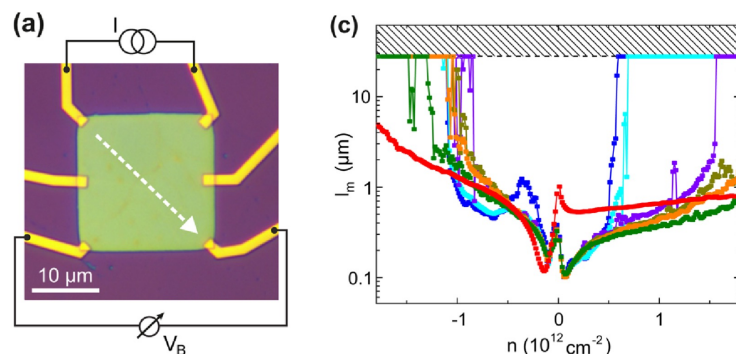
White *et al.*, *ACS Applied Nano Materials* 2023

Auton *et al.*, *Nat Communications* 2016

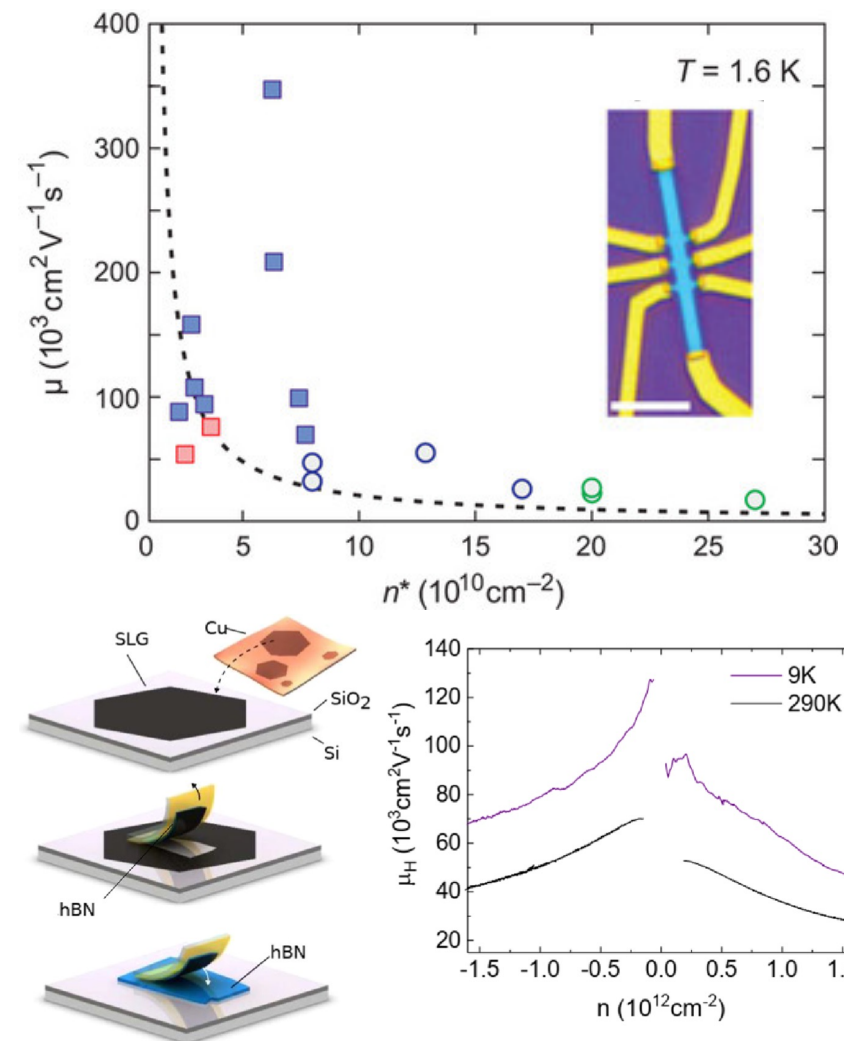


Ballistic Transport in Graphene

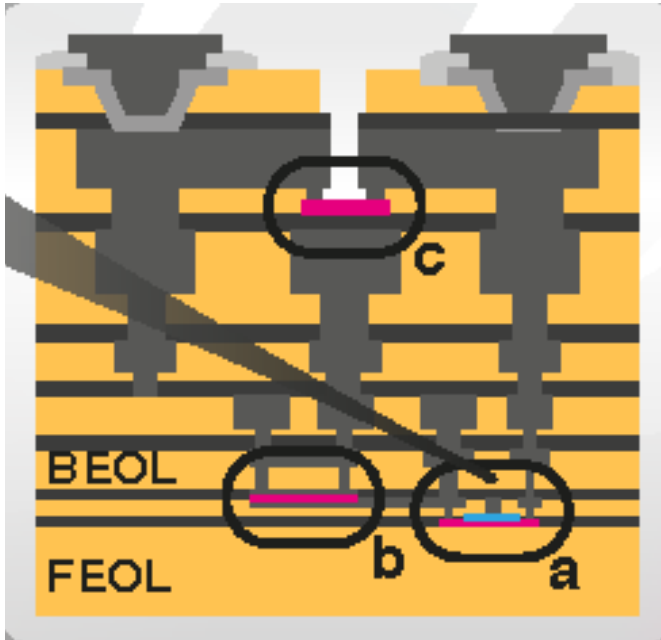
- Graphene: $>350,000 \text{ cm}^2/\text{Vs}$
- Exceptional mobility largely retained
 - On insulating substrates
 - At room temperature
 - With scalable material growth techniques (CVD)
- Mean free path $>28\mu\text{m}$ demonstrated in CVD-grown graphene
- Ballistic reflection especially important at the graphene edge



L. Banszerus, *et al.* *Nano Letters* **2016** 16 (2), 1387-1391
 L. Banszerus, *et al.* *Sci. Adv.* **2015** 1, e1500222
 D. De Fazio, *et al.* *ACS Nano*, **2019** 13 (8), 8926-8935



2D-CMOS Integration: Challenges



Neumaier, Pindl, Lemme, Nature Materials, 2019
Akinwande *et al.*, Nature, 2019
Illarionov *et al.*, Nature Communications, 2020
Quellmaltz *et al.*, Nature Communications, 2021
Lemme *et al.*, Nature Communications, 2022

Growth

- Catalytic CVD on metals
- Temperatures: 400-1000° C
- Quality

Transfer process

- Quality
- Automation

Etching

- Etch stop → ALE

Encapsulation

- ALD vs. 2D

Electrical contacts

- ✓ Graphene
- Semiconducting 2D

A number of **Engineering Challenges**

remain before we see 2D Materials-based electronics / optoelectronics



Addressed by the
**2D-
Experimental
Pilot Line**

2D Experimental Pilot Line

1. Development of tools & materials

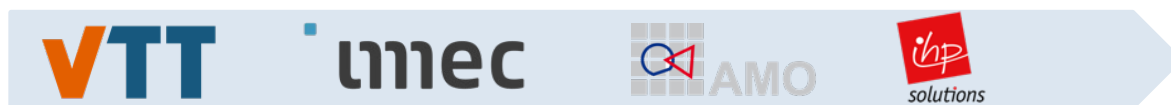
- H2020 project to develop technology (not a specific application)
- Start in 10/2020, 4 years, 20 M€ funding
- Goal: technology transfer to Europractice and European Industry



2. Development of module & platform



3. Multi-purpose wafer runs



Industrial Advisory
Board

X-FAB

AMS

NXP

Infineon

STMicroelectronics

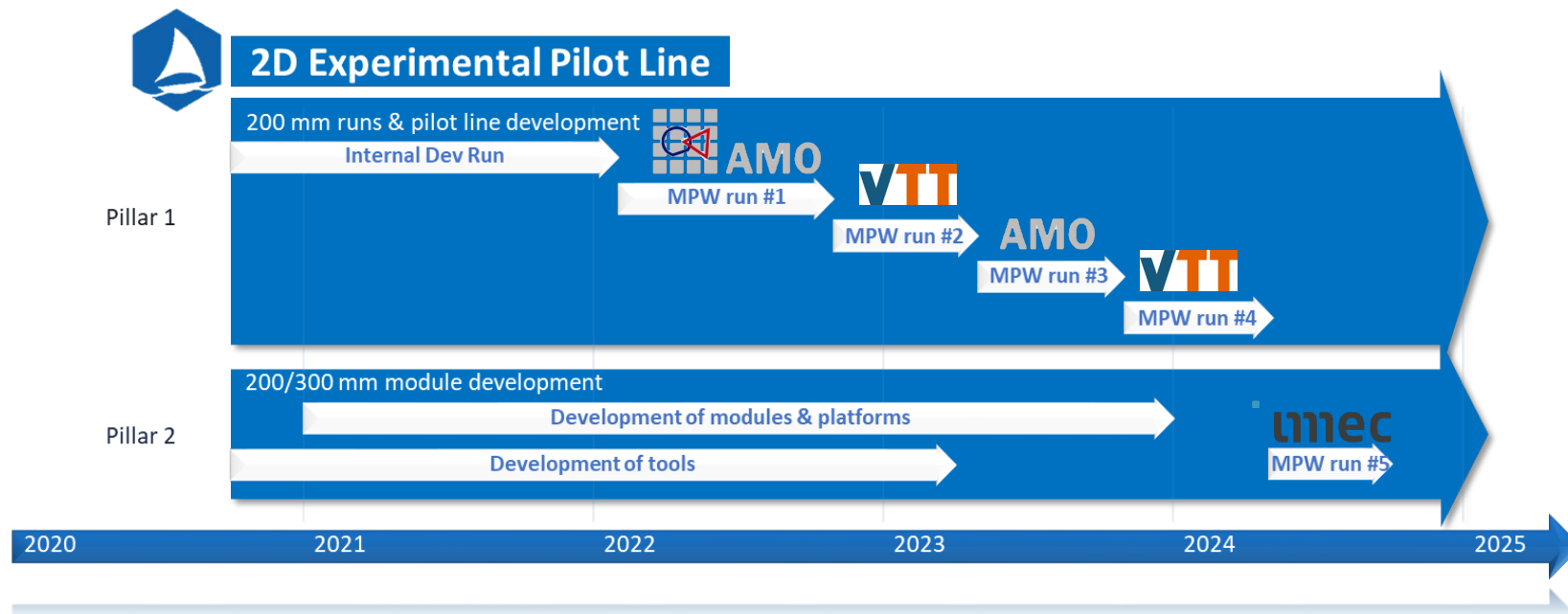
Emberion

Nokia

ELMOS

2D Experimental Pilot Line

2D EPL Project Timeline (MPW runs)



Run 1
AMO
Graphene Sensors
DELIVERED
Dec 2023

Run 2
VTT
Graphene Sensors
DELIVERED
June 2023

Run 3
AMO
Electronic Devices incl. Graphene Sensors
DELIVERED
Oct 2023

Run 4
VTT
Graphene Sensors devices on CMOS wafers
June 2024

Run 5
imec
TMDC based transistors
Oct 2024

+ additional runs

Development of tools, modules and platforms in parallel with the offer of MPW runs.

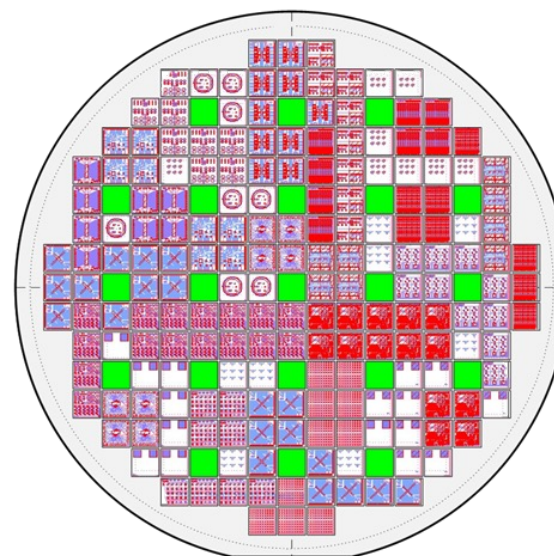
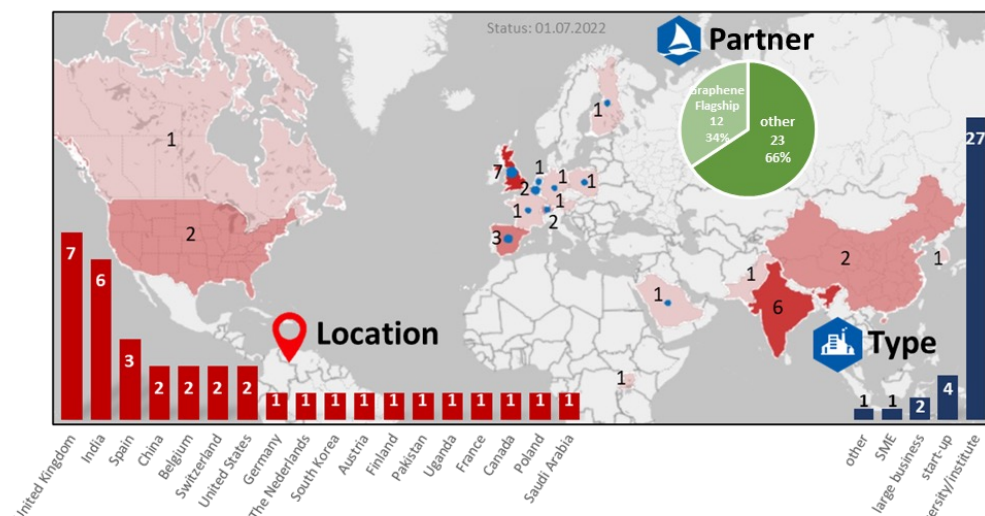


2D Experimental Pilot Line

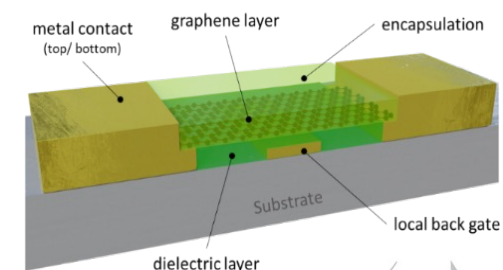
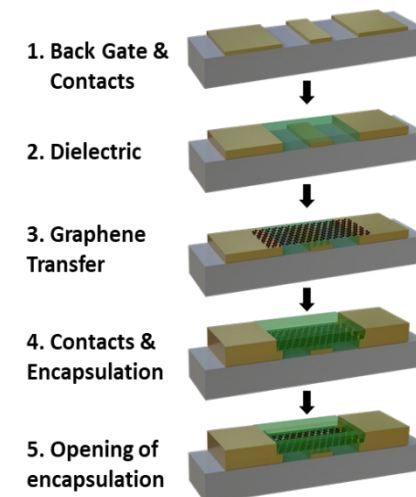
Multi-Project Wafer Run #1



Overall applications

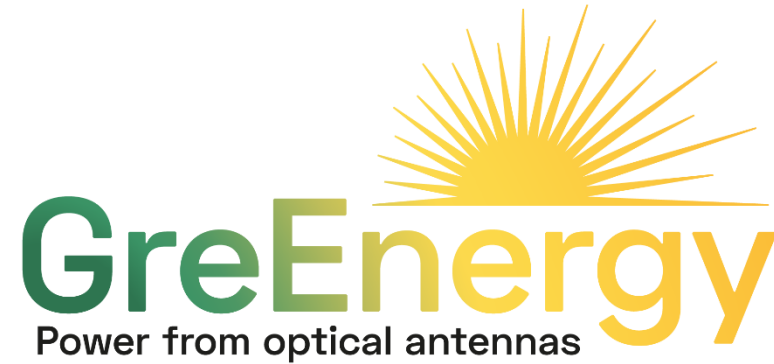


Mask with customer dies distributed over 8" wafer;
21 different designs,
108 order dies



35 applications => 14 participating customers

Thank you!



www.greenenergy-project.eu

www.linkedin.com/company/greenenergy-project



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